

Single N-channel MOSFET

ELM14408AA-N

■General description

ELM14408AA-N uses advanced trench technology to provide excellent $R_{ds(on)}$, low gate charge and low gate resistance.

■Features

- $V_{ds}=30V$
- $I_d=12A$ ($V_{gs}=10V$)
- $R_{ds(on)} < 13m\Omega$ ($V_{gs}=10V$)
- $R_{ds(on)} < 16m\Omega$ ($V_{gs}=4.5V$)

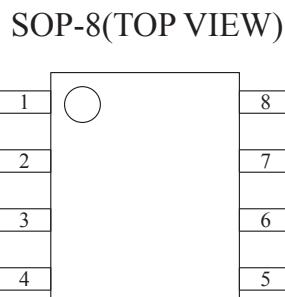
■Maximum absolute ratings

Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V_{ds}	30	V	
Gate-source voltage	V_{gs}	± 12	V	
Continuous drain current Ta=25°C	I_d	12	A	1
Ta=70°C	I_d	10		
Pulsed drain current	I_{dm}	80	A	2
Avalanche current	I_{av}	30	A	2, 5
Repetitive avalanche energy	E_{av}	100	mJ	2, 5
Power dissipation Ta=25°C	P_d	3.0	W	
Ta=70°C	P_d	2.1		
Junction and storage temperature range	T_j, T_{stg}	-55 to 150	°C	

■Thermal characteristics

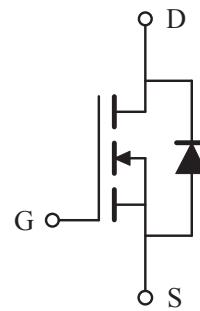
Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	$t \leq 10s$	$R_{\theta ja}$	23	40	°C/W	1
Maximum junction-to-ambient	Steady-state		48	65	°C/W	
Maximum junction-to-lead	Steady-state	$R_{\theta jl}$	12	16	°C/W	3

■Pin configuration



Pin No.	Pin name
1	SOURCE
2	SOURCE
3	SOURCE
4	GATE
5	DRAIN
6	DRAIN
7	DRAIN
8	DRAIN

■Circuit



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■Electrical characteristics

$T_a=25^\circ C$

Parameter	Symbol	Condition		Min.	Typ.	Max.	Unit
STATIC PARAMETERS							
Drain-source breakdown voltage	BVdss	Id=250 μA , Vgs=0V		30			V
Zero gate voltage drain current	Idss	Vds=24V, Vgs=0V			0.003	1.000	μA
			Tj=55°C			5.000	
Gate-body leakage current	Igss	Vds=0V, Vgs=±12V				100	nA
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=250 μA		1.0	1.5	2.5	V
On state drain current	Id(on)	Vgs=4.5V, Vds=5V		40			A
Static drain-source on-resistance	Rds(on)	Vgs=10V, Id=12A			10.5	14.0	$m\Omega$
			Tj=125°C		16.0	21.0	
		Vgs=4.5V, Id=10A			13.0	16.5	$m\Omega$
Forward transconductance	Gfs	Vds=5V, Id=10A		30	48		S
Diode forward voltage	Vsd	Is=1A, Vgs=0V			0.76	1.00	V
Max. body-diode continuous current	Is					4.5	A
DYNAMIC PARAMETERS							
Input capacitance	Ciss	Vgs=0V, Vds=15V, f=1MHz			1020	1200	pF
Output capacitance	Coss				320		pF
Reverse transfer capacitance	Crss				80		pF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz			0.25	0.50	Ω
SWITCHING PARAMETERS							
Total gate charge	Qg	Vgs=4.5V, Vds=15V, Id=12A			10.3	12.5	nC
Gate-source charge	Qgs				2.1		nC
Gate-drain charge	Qgd				3.9		nC
Turn-on delay time	td(on)	Vgs=10V, Vds=15V Rl=1.2 Ω , Rgen=3 Ω			3.9	5.5	ns
Turn-on rise time	tr				3.0	6.0	ns
Turn-off delay time	td(off)				19.2	30.0	ns
Turn-off fall time	tf				2.6	5.0	ns
Body diode reverse recovery time	trr	Ir=12A, dl/dt=100A/ μs			26	32	ns
Body diode reverse recovery charge	Qrr	Ir=12A, dl/dt=100A/ μs			18	32	nC

NOTE :

1. The value of $R_{\theta ja}$ is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with $T_a=25^\circ C$. The value in any given applications depends on the user's specific board design. The current rating is based on the $t \leq 10s$ thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The $R_{\theta ja}$ is the sum of the thermal impedance from junction to lead $R_{\theta jl}$ and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^\circ C$. The SOA curve provides a single pulse rating.



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■ Typical electrical and thermal characteristics

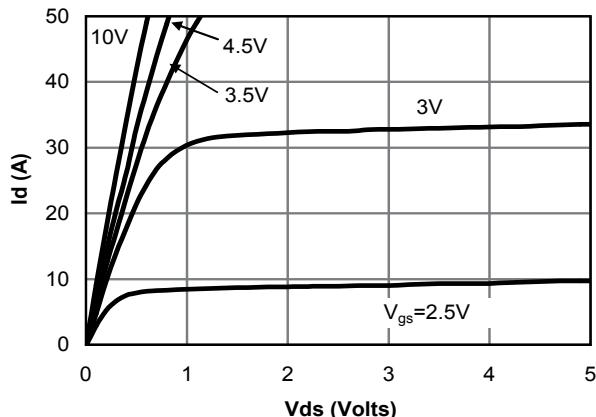


Fig 1: On-Region Characteristics

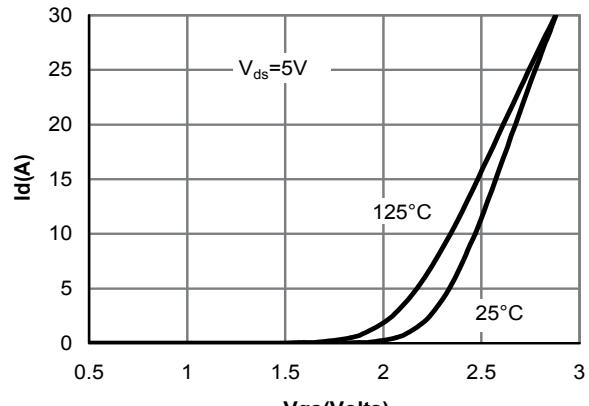


Figure 2: Transfer Characteristics

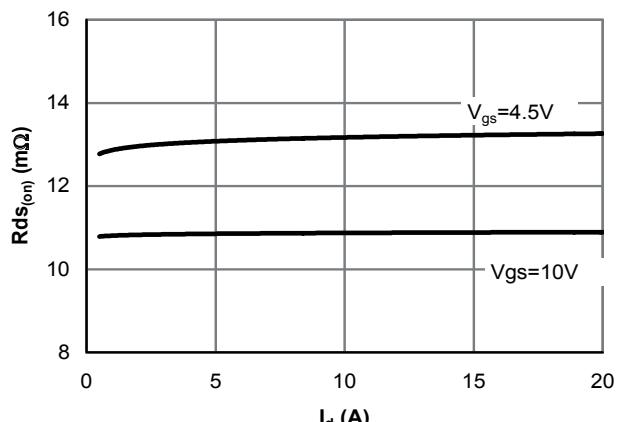


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

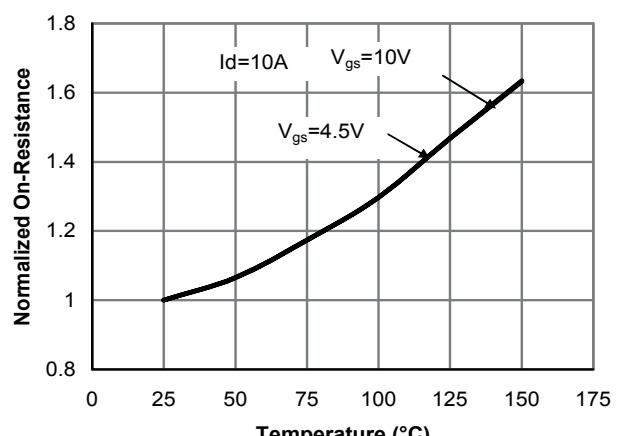


Figure 4: On-Resistance vs. Junction Temperature

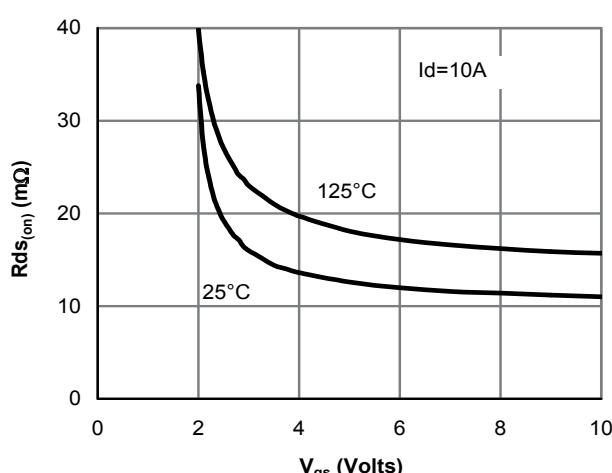


Figure 5: On-Resistance vs. Gate-Source Voltage

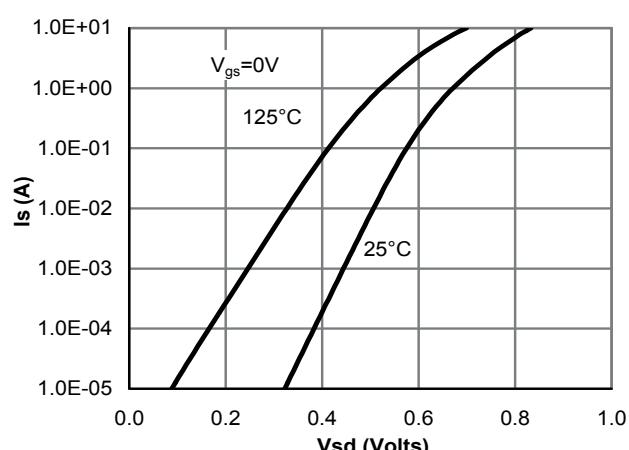
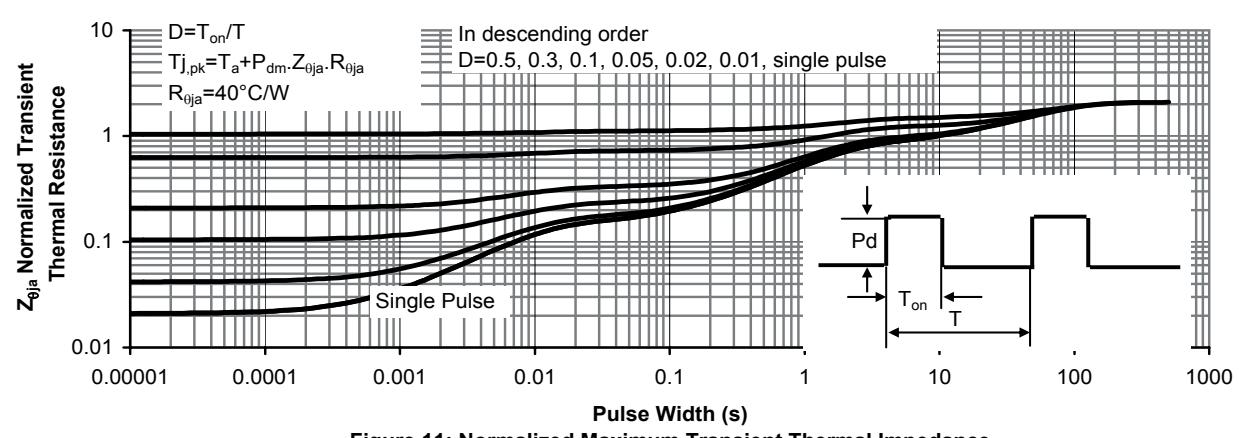
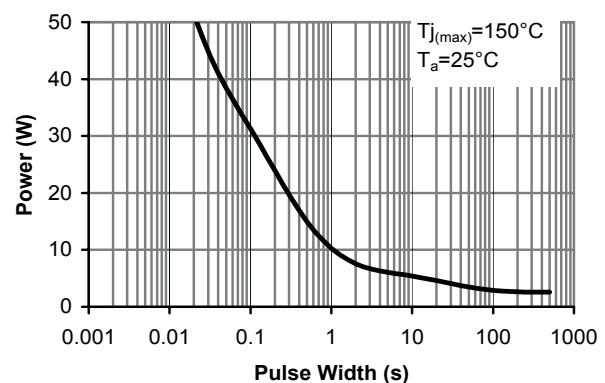
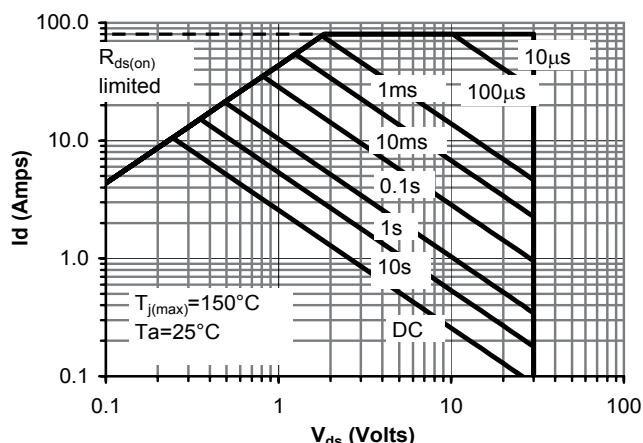
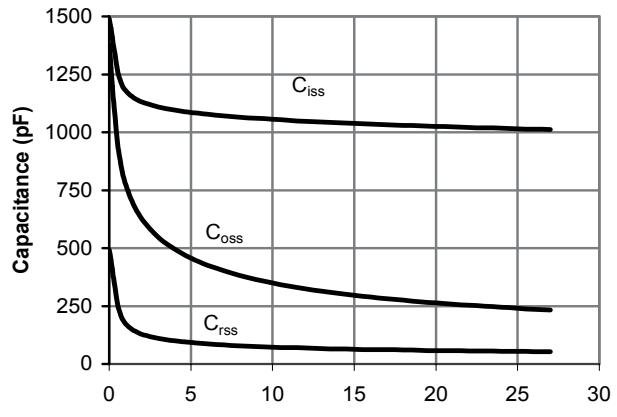
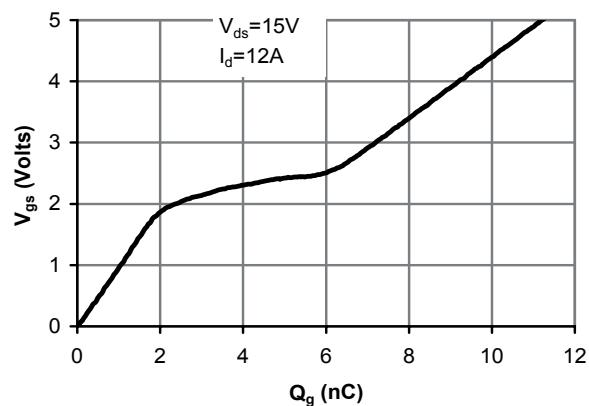


Figure 6: Body-Diode Characteristics

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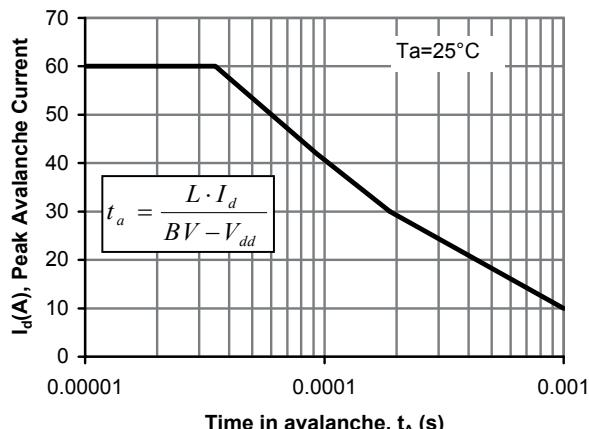


Figure 12: Avalanche capability

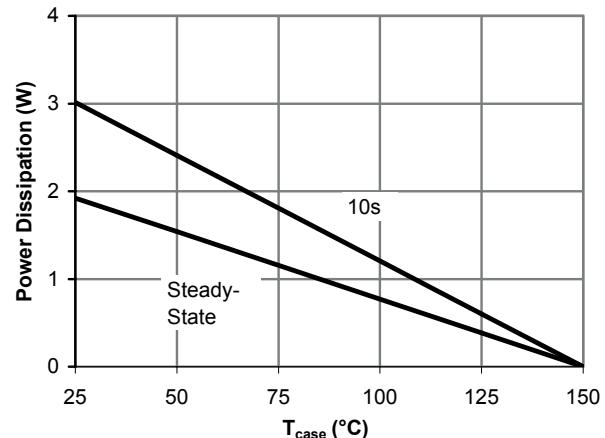


Figure 13: Power De-rating (Note A)